Features：

- **n** Isolated mounting base 3000V~
- **n** Solder joint technology with increased power cycling capability
- **n** Space and weight saving

Typical Applications：

- **n** Various rectifiers
- **n** DC supply for PWM inverter

V_{RRM}	Type & Outline
600V	MDC160-06-229H3
800V	MDC160-08-229H3
1000V	MDC160-10-229H3
1200V	MDC160-12-229H3
1400V	MDC160-14-229H3
1600V	MDC160-16-229H3
1800V	MDC160-18-229H3

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T_j(°C)	VALUE			UNIT
				Min	Type	Max	
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled, T_C=100°C	150			160	A
$I_{F(RMS)}$	RMS forward current					251	A
I_{RRM}	Repetitive peak current	at V_{RRM}	150			12	mA
I_{FSM}	Surge forward current	10ms half sine wave V_R=0.6V_{RRM}	150			4	kA
I^2t	I^2t for fusing coordination					80	A^2S*10^3
V_{FO}	Threshold voltage		150			0.85	V
r_F	Forward slope resistance					1.25	mΩ
V_{FM}	Peak forward voltage	I_{FM}=480A	25			1.50	V
$R_{th(j-c)}$	Thermal resistance Junction to case	Single side cooled per chip				0.20	°C /W
$R_{th(c-h)}$	Thermal resistance case to heatsink	Single side cooled per chip				0.08	°C /W
V_{iso}	Isolation voltage	50Hz,R.M.S,t=1min, I_{iso}:1mA(max)		3000			V
F_m	Terminal connection torque(M6)			4.5		6	N·m
	Mounting torque(M6)			4.5		6	N·m
T_{vj}	Junction temperature			-40		150	°C
T_{stg}	Stored temperature			-40		125	°C
W_t	Weight				165		g
Outline	229H3						

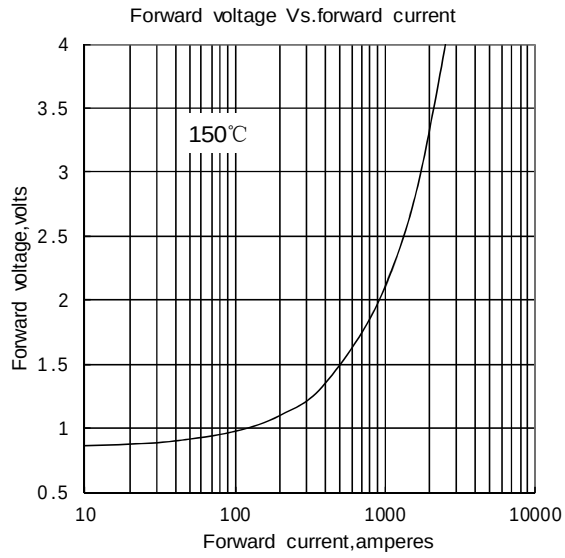


Fig1

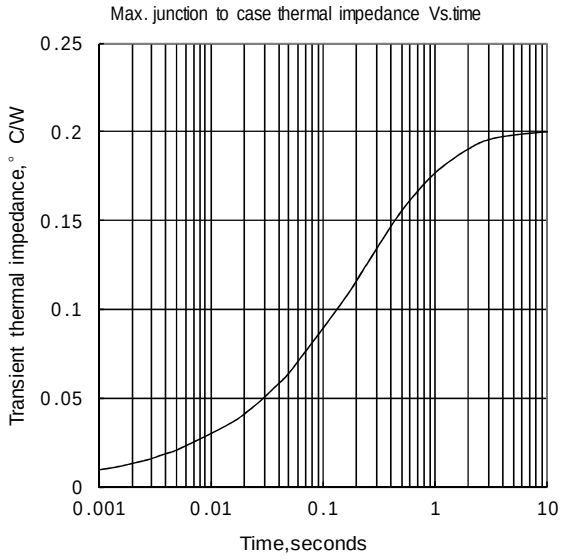
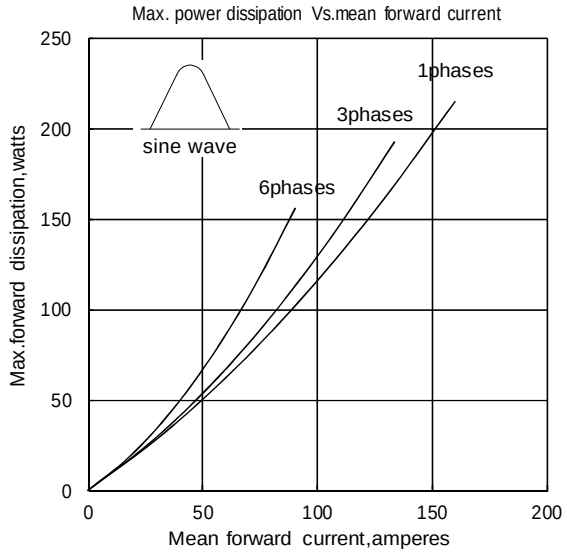


Fig2



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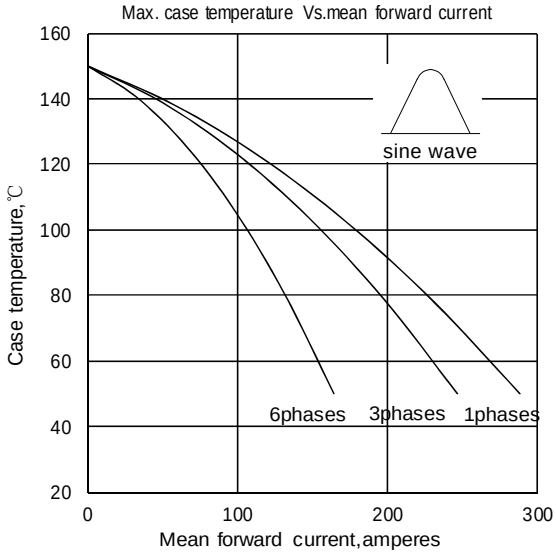


Fig4

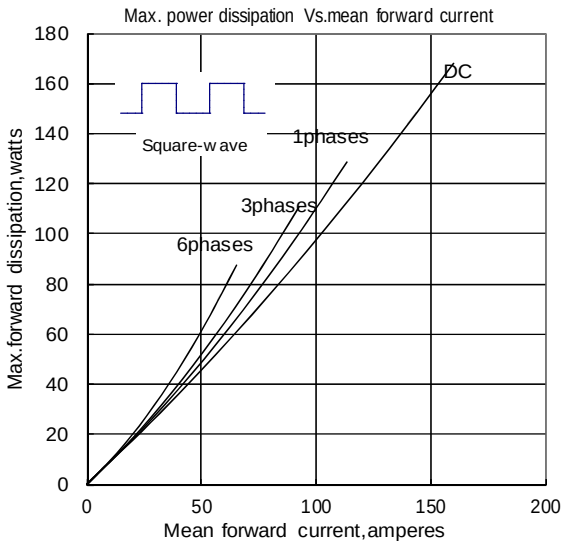


Fig5

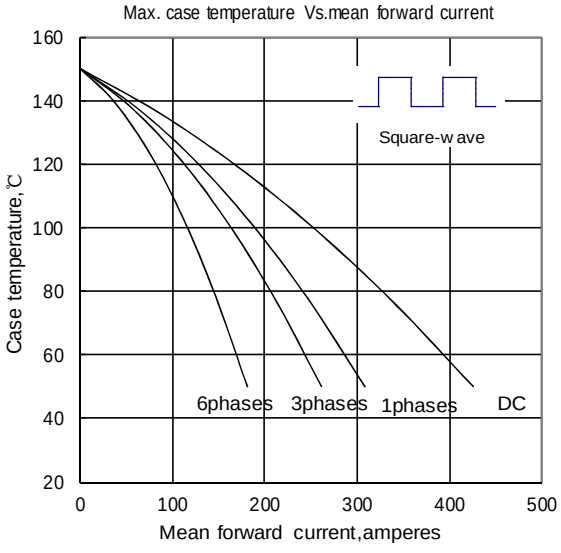


Fig6

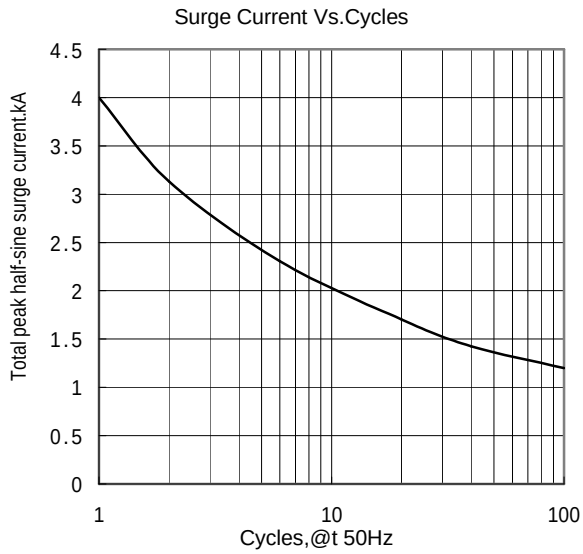


Fig7

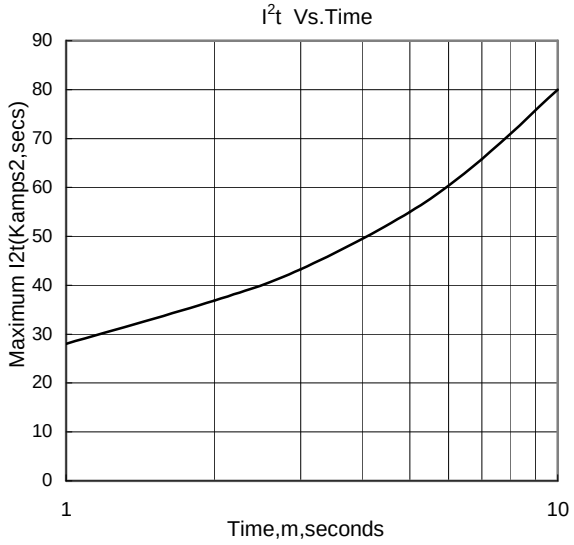
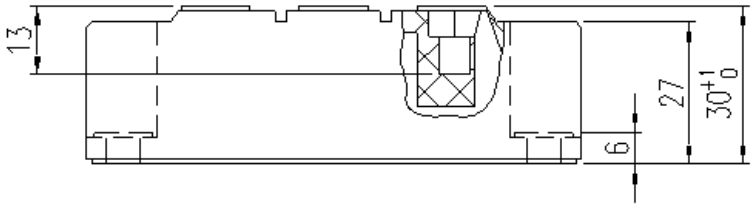
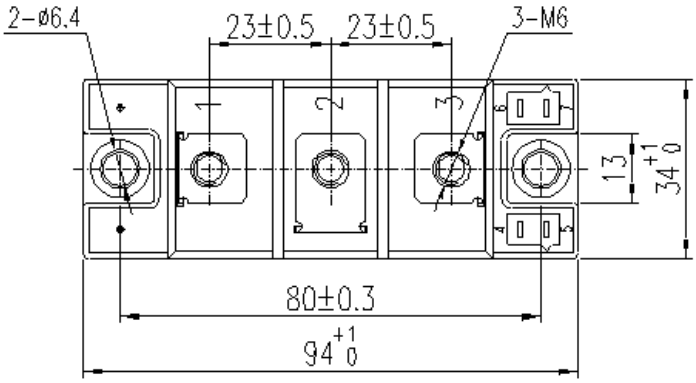
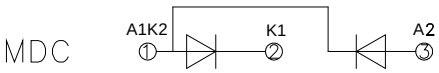


Fig8

Outline:







Unmarked dimensional tolerance：±0.5mm